

Item Name: DGS2_RC12_BOM_R10
Revision: C1.2
Date: 2022-06-22

Company:
Contact:
Email:

A. PCB Specifications

A.1. Dimension X:	1.75
A.2. Dimension Y:	0.82
A.3. Layers:	2
A.4. Material:	FR4
A.5. Copper Weight (external):	1 oz
A.6. Copper Weight (internal):	N/A
A.7. Finish Plating:	HASL
A.8. Finish Thickness:	0.062
A.9. Soldermask Color:	Green
A.10. Silkscreen Color:	White

B. PCB Fabrication

- B.1. Fabrication shall be to the latest revision of IPC-6012, CLASS II spec.
- B.2. PCB Specifications outlined above shall be followed.
- B.3. Materials shall be in compliance with EU RoHS Directive 2002/95.
- B.4. Silkscreen shall be non-conductive ink, to be printed only over soldermask.
- B.5. All Plated Thru Holes (PTH) are to be plated and all Non-Plated Thru Holes (NPTH) are not to be plated.
- B.6. All castellations are to be free of metal burrs.

C. PCB Assembly

- C.1. Materials shall be in compliance with EU RoHS Directive 2002/95.
- C.2. Rework solder and flux must be compliant with a no-clean process.
- C.3. Flux shall be non-corrosive, non-conductive.
- C.4. Solder shall be lead-free.
- C.5. All thru-hole component lead protrusions shall be trimmed to not exceed 0.060".
- C.6. All thru-hole components shall be fully flooded with solder.
- C.7. Following assembly, all flux requiring cleaning must be removed using appropriate cleaning solutions.
- C.8. Upon completion of assembly, board arrays are to be separated by a non-manual, machine process that minimizes mechanical impact.

D. General

- D.1. All dimensions are in INCHES, unless otherwise specified.